CAT28C16V3

16K-Bit CMOS POWER MISER™ E2PROM

FEATURES

- Fast Read Access Times: 700 ns
- Low Power CMOS Dissipation:
 - -Active: 10mA Max. -Standby: 50µA Max.
- Simple Write Operation:
 - -On-Chip Address and Data Latches
 - -Self-Timed Write Cycle with Auto-Clear

- Fast Nonvolatile Write Cycle: 20ms Max
- End of Write Detection: DATA Polling
- Hardware Write Protection
- CMOS and TTL Compatible I/O
- 10,000 Program/Erase Cycles
- 10 Year Data Retention

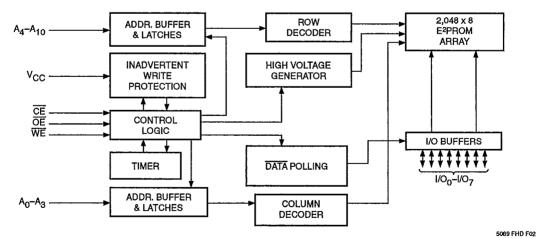
DESCRIPTION

The CAT28C16V3 is a fast, low power, 3V-only CMOS E²PROM organized as 2K x 8 bits. It requires a simple interface for in-system programming. On-chip address and data latches, self-timed write cycle with auto-clear and Vcc power up/down write protection eliminate additional timing and protection hardware. DATA Polling signals the start and end of the self-timed write cycle.

Additionally, the CAT28C16V3 features hardware write protection.

The CAT28C16V3 is manufactured using Catalyst's advanced CMOS floating gate technology. It is designed to endure 10,000 program/erase cycles and has a data retention of 10 years. The device is available in JEDEC approved 24 pin DIP and SO or 32 pin PLCC packages.

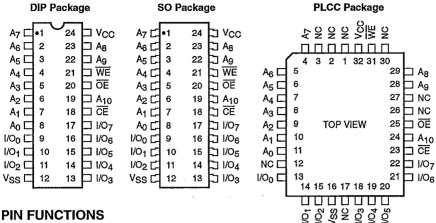
BLOCK DIAGRAM



TD 5090

5089 FHD F01

PIN CONFIGURATION



D1 11	
Pin Name	Function
A ₀ -A ₁₀	Address Inputs
1/00-1/07	Data Inputs/Outputs
CE	Chip Enable
<u>OE</u>	Output Enable
WE	Write Enable
Vcc	3V Supply
Vss	Ground
NC .	No Connect

MODE SELECTION

Mode	CE	WE	ŌĒ	1/0	Power	
Read	L	Н	L	Dout	ACTIVE	
Byte Write (WE Controlled)	L	\	Н	DiN	ACTIVE	
Byte Write (CE Controlled)	\ <u>\</u>	L	Н	D _{IN}	ACTIVE	
Standby, and Write Inhibit	Н	Х	Х	High-Z	STANDBY	
Read and Write Inhibit	Х	Н	Н	High-Z	ACTIVE	

CAPACITANCE TA = 25°C, f = 1.0 MHz, V_{CC} = 5V

Symbol	Test	Max.	Units	Conditions
C _{I/O} (1)	Input/Output Capacitance	10	pF	V _{I/O} = 0V
C _{IN} (1)	Input Capacitance	6	pF	V _{IN} = 0V

⁽¹⁾ This parameter is tested initially and after a design or process change that affects the parameter.

CATALYST SEMICONDUCTOR.

ABSOLUTE MAXIMUM RATINGS*

*COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions outside of those listed in the operational sections of this specification is not implied. Exposure to any absolute maximum rating for extended periods may affect device performance and reliability.

RELIABILITY CHARACTERISTICS

Symbol	Parameter	Min.	Max.	Units	Test Method
N _{END} ⁽¹⁾	Endurance	10,000		Cycles/Byte	MIL-STD-883, Test Method 1033
T _{DR} (1)	Data Retention	100		Years	MIL-STD-883, Test Method 1008
V _{ZAP} (1)	ESD Susceptibility	2000		Volts	MIL-STD-883, Test Method 3015
I _{LTH} (1)(4)	Latch-Up	100		mA	JEDEC Standard 17

D.C. OPERATING CHARACTERISTICS

CAT28C16V3 $T_A = 0^{\circ}$ C to +70°C, $V_{CC} = 3V \pm 10\%$, unless otherwise specified.

		Limits				
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
lccc ⁽⁵⁾	Vcc Current (Operating, CMOS)			10	mA	CE = OE = V _{ILC} , f = 1/t _{RC} min, All I/O's Open
I _{SBC} ⁽⁶⁾	V _{CC} Current (Standby, CMOS)			50	μА	CE = V _{IHC} , All I/O's Open
l _{Ll}	Input Leakage Current	-10		10	μΑ	V _{IN} = GND to V _{CC}
llo	Output Leakage Current	-10		10	μА	V _{OUT} = GND to V _{CC} , CE = V _{IH}
VIH(6)	High Level Input Voltage	V _{CC} -0.3		V _{CC} +0.3	٧	
V _{IL} (5)	Low Level Input Voltage	-0.3		0.3	٧	
Vон	High Level Output Voltage	V _{CC} -0.3			٧	l _{OH} = −10μA
VoL	Low Level Output Voltage			0.3	V	l _{OL} = 10mA
Vwi	Write Inhibit Voltage	2.0			٧	

Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter.

(2) The minimum DC input voltage is -0.5V. During transitions, inputs may undershoot to -2.0V for periods of less than 20 ns. Maximum DC voltage on output pins is V_{CC} +0.5V, which may overshoot to V_{CC} +2.0V for periods of less than 20 ns.

(3) Output shorted for no more than one second. No more than one output shorted at a time.

(4) Latch-up protection is provided for stresses up to 100mA on address and data pins from -1V to V_{CC} +1V.

(5) $V_{ILC} = -0.3V$ to +0.3V.

(6) V_{IHC} = V_{CC} -0.3V to V_{CC} +0.3V.

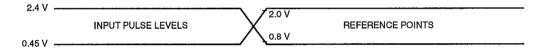
CATALYST SEMICONDUCTOR

A.C. CHARACTERISTICS, Read Cycle

CAT28C16V3 $T_A = 0$ °C to +70°C, $V_{CC} = 3V \pm 10\%$, unless otherwise specified.

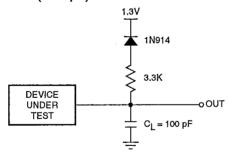
		28C16	28C16V3-20	
Symbol	Parameter	Min.	Max.	Units
trc	Read Cycle Time	700		ns
tcE	CE Access Time		700	ns
t _{AA}	Address Access Time		700	ns
toE	OE Access Time		450	ns
t _{LZ} (1)	CE Low to Active Output	10		ns
toLZ ⁽¹⁾	OE Low to Active Output	10		ns
t _{HZ} (1)(7)	CE High to High-Z Output		80	ns
t _{OHZ} (1)(7)	OE High to High-Z Output		80	ns
toH ⁽¹⁾	Output Hold from Address Change	100		ns

Figure 1. A.C. Testing Input/Output Waveform⁽⁸⁾



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Figure 2. A.C. Testing Load Circuit (example)



CI INCLUDES JIG CAPACITANCE

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Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter.

(7) Output floating (High-Z) is defined as the state when the external data line is no longer driven by the output buffer.

(8) Input rise and fall times (10% and 90%) < 10 ns.

CATALYST SEMICONDUCTOR -

A.C. CHARACTERISTICS, Write Cycle

CAT28C16V3 T_A = 0° C to $+70^{\circ}$ C, $V_{CC} = 3V \pm 10\%$, unless otherwise specified.

Symbol		28C16	28C16V3-20		
	Parameter	Min.	Max.	Units	
twc	Write Cycle Time		20	ms	
tas	Address Setup Time	10		ns	
tah	Address Hold Time	150		ns	
tcs	Write Setup Time	0		ns	
tсн	Write Hold Time	0		ns	
tcw ⁽⁹⁾	CE Pulse Time	200		ns	
toes	OE Setup Time	20		ns	
toeH	OE Hold Time	20		ns	
twp ⁽⁹⁾	WE Pulse Width	200		ns	
tos	Data Setup Time	100		ns	
t _{DH}	Data Hold Time	20		ns	
t _{DL}	Data Latch Time	100		ns	
t _{INIT} (1)	Write Inhibit Period After Power-up	10	30	ms	

 ⁽¹⁾ This parameter is tested initially and after a design or process change that affects the parameter.
(9) A write pulse of less than 20ns duration will not initiate a write cycle.

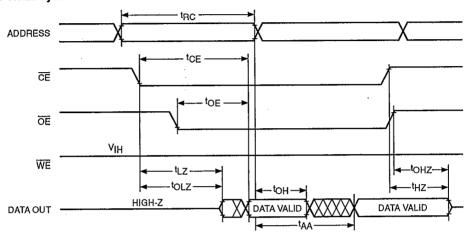
DEVICE OPERATION

Read

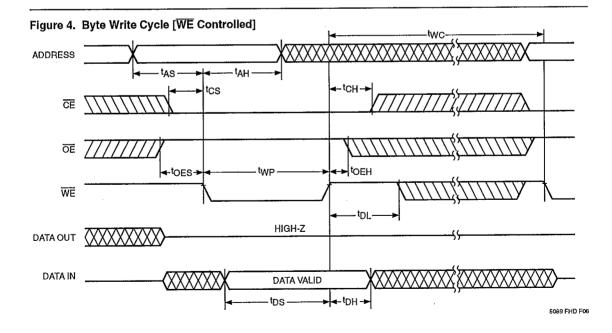
Data stored in the CAT28C16V3 is transferred to the data bus when \overline{WE} is held high, and both \overline{OE} and \overline{CE} are

held low. The data bus is set to a high impedance state when either \overline{CE} or \overline{OE} goes high. This 2-line control architecture can be used to eliminate bus contention in a system environment.

Figure 3. Read Cycle



5089 FHD F05



SOBO EHD EOZ

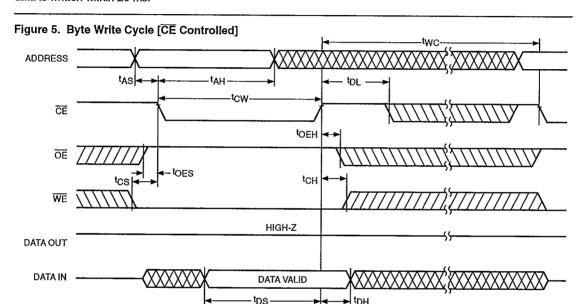
CATALYST SEMICONDUCTOR.

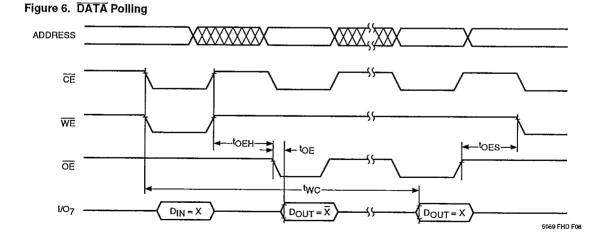
Byte Write

A write cycle is executed when both \overline{CE} and \overline{WE} are low, and \overline{OE} is high. Write cycles can be initiated using either \overline{WE} or \overline{CE} , with the address input being latched on the falling edge of \overline{WE} or \overline{CE} , whichever occurs last. Data, conversely, is latched on the rising edge of \overline{WE} or \overline{CE} , whichever occurs first. Once initiated, a byte write cycle automatically erases the addressed byte and the new data is written within 20 ms.

DATA Polling

DATA polling is provided to indicate the completion of a byte write cycle. Once a byte write cycle is initiated, attempting to read the last byte written will output the complement of that data on I/O₇ (I/O₀–I/O₆ are indeterminate) until the programming cycle is complete. Upon completion of the self-timed byte write cycle, all I/O's will output true data during a read cycle.





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HARDWARE DATA PROTECTION

The following is a list of hardware data protection features that are incorporated into the CAT28C16V3.

- (1) V_{CC} sense provides for write protection when V_{CC} falls below 2.0V min.
- (2) A power on delay mechanism, t_{INIT} (see AC charac-

CATALYST SEMICONDUCTOR -

- teristics), provides a 10 to 30 ms delay before a write sequence, after V_{CC} has reached 2.0V min.
- (3) Write inhibit is activated by holding any one of OE low, CE high or WE high.
- (4) Noise pulses of less than 20 ns on the WE or CE inputs will not result in a write cycle.